

## 23 Packaging Of Electronic Equipments 2 Cu

Each May, the Continuing Education Division of the T.J.Watson School of Engineering, Applied Science and Technology at the State University of New York at Binghamton sponsors an Annual Symposium in Electronics Packaging in cooperation with local professional societies (IEEE, ASME, SME, IEPS) and UnIPEG (the University-Industry Partnership for Economic Growth.) Each volume of this Electronics Packaging Forum series is based on the the preceding Symposium, with Volume Two based on the 1990 presentations. The Preface to Volume One included a brief definition of the broad scope of the electronics packaging field with some comments on why it has recently assumed such a more prominent priority for research and development. Those remarks will not be repeated here; at this point it is assumed that the reader is a professional in the packaging field, or possibly a student of one of the many academic disciplines which contribute to it. It is worthwhile repeating the series objectives, however, so the reader will be clear as to what might be expected by way of content and level of each chapter.

### Scientific and Technical Aerospace Reports

Moisture Sensitivity of Plastic Packages of IC Devices provides information on the state-of-the-art techniques and methodologies related to moisture issues in plastic packages. The most updated, in-depth and systematic technical and theoretical approaches are addressed in the book. Numerous industrial applications are provided, along with the results of the most recent research and development efforts, including, but not limited to: thorough exploration of moisture's effects based on lectures and tutorials by the authors, consistent focus on solution-based approaches and methodologies for improved reliability in plastic packaging, emerging theories and cutting-edge industrial applications presented by the leading professionals in the field. Moisture plays a key role in the reliability of plastic packages of IC devices, and moisture-induced failures have become an increasing concern with the development of advanced IC devices. This second volume in the Micro- and Opto-Electronic Materials, Structures, and Systems series is a must-read for researchers and engineers alike.

The last twenty years have seen major advances in the electronics industry. Perhaps the most significant aspect of these advances has been the significant role that electronic equipment plays in almost all product markets. Even though electronic equipment is used in a broad base of applications, many future applications have yet to be conceived. This versatility of electronics has been brought about primarily by the significant advances that have been made in integrated circuit technology. The electronic product user is rarely aware of the integrated circuits within the equipment. However, the user is often very aware of the size, weight, modularity, maintainability, aesthetics, and human interface features of the product. In fact, these are aspects of the products that often are instrumental in determining its success or failure in the marketplace. Optimizing these and other product features is the primary role of Electronic Equipment Packaging Technology. As the electronics industry continues to provide products that operate faster than their predecessors in a smaller space with a reduced cost per function, the role of electronic packaging technology will assume an even greater role in the development of cost-effective products.

Lists citations with abstracts for aerospace related reports obtained from world wide sources and announces documents that have recently been entered into the NASA Scientific and Technical Information Database.

Nanotechnologies are being applied to the biotechnology area, especially in the area of nano material synthesis. Until recently, there has been little research into how to implement nano/bio materials into the device level. "Nano and Bio Electronics Packaging" discusses how nanofabrication techniques can be used to customize packaging for nano devices with applications to biological and biomedical research and products. Covering such topics as nano bio sensing electronics, bio device packaging, NEMs for Bio Devices and much more.

Includes articles on international business opportunities.

Business establishments, employment, and taxable pay rolls, by industry groups, under Old-Age and Survivors Program.

With the proliferation of packaging technology, failure and reliability have become serious concerns. This invaluable reference details processes that enable detection, analysis and prevention of failures. It provides a comprehensive account of the failures of device packages, discrete component connectors, PCB carriers and PCB assemblies.

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